

Document Title		PACKAGE OUTLINE, TSSOP 4.40mm BODY			
Doc ID #	21-0066	New Rev	I	Effective Date	

Originator	Gauri Patel	Facility	PACKAGING DEPT.
Phone #	6729	883	<input type="checkbox"/> SMD
ECN Type	Permanent	Expiration	Date
Matl. or Masks Affected	N/A	Disposition	N/A

For Fab Only

Area		Level	Class I
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For Product Related Only

Die Type	
External Number	
Business Unit	VP Name

For Data Sheet Only

Print Review Req'd	N/A
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Root Cause or Justification of ECN

ADD DIMENSION H IN THE DIAGRAM. VARIATIONS TABLE DIMENSION CORRECTIONS.

Description of Change

From	To
NOTE 9 BENT LEAD	NOTE 9 BENT LEAD 0.10 MM MAX.
VARIATIONS TABLE JEDEC MO-153 AC, MILLIMETERS MAX = 5.10	VARIATIONS TABLE JEDEC MO-153 AC, MILLIMETERS MAX = 6.60
BENT LEAD DIAG. CORRECTION bbb DIMENSION REFERENCED TO NOTE 6.	BENT LEAD DIAG. CORRECTION bbb DIMENSION REFERENCED TO NOTE 9.
	DIMENSION H ADDED TO TOP VIEW DIAGRAM.

Approvals

Name	Functional Title	Date	Name	Functional Title	Date
Pkngng. Engr.					
S. Chinnusamy					
C. Keene					

Additional Notification (refer to 11-0001)

HQ; Maxim North; J. Moist; L. Jackson; M. Rubenzahl; S. Sung; S. Schroeder; A. Arreola; A. Wichman; D. Goldbaum; E. Evans; Colorado/Austin/Plano Design Centers. Louis Berman; Norman Nakamura; Adolfo Ylagan. Vendors: Carsem M, NSEB/UTL, Carsem S., ATP.
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Other Docs Affected No	
DC Submission Date	DC Processor Name

